



Advance Product Change Notification

202309003A : Introduction of Multi-Source Optical Shrink Versions of Various CAN/LIN Products

Note: This notice is NXP Company Proprietary.

Issue Date: Nov 02, 2023

Here is your personalized notification about a NXP general announcement.

For detailed information we invite you to [view this notification online](#)

Management summary

NXP Product Line In-Vehicle Networking (PL IVN) will be introducing multi-source optical shrink versions of products TJA1021, TJA1022, TJA1024, TJA1027, TJA1029, TJA1042, TJA1043, TJA1044, TJA1046 and TJA1057.

Change Category

<input type="checkbox"/> Wafer Fab Process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Test Process	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Errata
<input checked="" type="checkbox"/> Wafer Fab Location	<input checked="" type="checkbox"/> Assembly Location	<input type="checkbox"/> Packing/Shipping/Labeling	<input checked="" type="checkbox"/> Test Location	<input type="checkbox"/> Electrical spec./Test coverage
<input type="checkbox"/> Firmware <input checked="" type="checkbox"/> Other: Optical shrink				

PCN Overview

Description

For the PL IVN CAN/LIN products TJA1021, TJA1022, TJA1024, TJA1027, TJA1029, TJA1042, TJA1043, TJA1044, TJA1046 and TJA1057 optical shrink product versions will be introduced. The Bill-of-Material (BoM) of those new shrink product versions will be using copper (Cu) bondwire, with the associated mold compound and die attach. These new product versions will be introduced as multi-source, i.e. using multiple front-end diffusion waferfabs and back-end assembly and final test sites.

This Advanced PCN (A-PCN) is clarifying which products are affected and provides a high-level view of the changes with respect to the current released 'baseline' products. The actual changes per product will be announced by final PCNs, attached to which will be the qualification and release documentation. The final PCN will also contain instructions on how to obtain samples or place production orders for these new product versions. Planning for these final PCNs per product is provided in the attachment to this A-PCN, instructions on how to obtain this document are given

below under the heading 'Remarks'.

Note that there is no need or use to respond to this A-PCN, there is nothing to accept or reject, it is purely pre-informing you of upcoming changes (please ignore the section 'Timing and Logistics' below).

Reason

These changes will help to continue NXP's Global Business Continuity Management process to establish an industrial base that is agile, robust and can reliably service the long term forecasted market growth of IVN products.

Product Availability

Sample Information

Sample Planning follows with the final PCN

Production

Shipment dates are product specific, see attached plan

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Disposition of Old Products

N/A

Additional information

Self qualification:[view online](#)

Timing and Logistics

The Self Qualification Report will be ready on Dec 31, 2023.

The Final PCN is planned to be issued on: Dec 31, 2023.

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Dec 02, 2023.

N/A

Remarks

Please use the link 'view online' under the heading 'Additional information' above, to log in to the NXP e-PCN system you're subscribed to, in order to obtain the attached document with relevant detailed information from the tab 'Files'.

Should you not be able to obtain this document, please contact your NXP sales representative or the e-mail address mentioned below under 'Contact and Support'.

In the NXP e-PCN system on the tab 'Products' you can see a list of your affected part numbers. There is no need or use to respond to this Advanced PCN (A-PCN), which is only meant to pre-inform you of upcoming changes. Upon NXP release of an optical shrink product version, a final PCN will be provided with all the detail change information and release reports. At such time the new orderable NXP 12NC part numbers will be provided, and samples can be ordered or production orders placed.

Related Notification

Notification	Issue Date	Effective Date	Title
202302005I	Feb 17, 2023	Mar 17, 2023	TJA1021 Datasheet Update

202302006I	Feb 17, 2023	Mar 17, 2023	TJA1028 Datasheet Update
202302007I	Feb 17, 2023	Mar 17, 2023	TJA1042 Datasheet Update
202302008I	Feb 17, 2023	Mar 17, 2023	TJA1044 Datasheet Update
202302010I	Feb 17, 2023	Mar 17, 2023	TJA1057 Datasheet Update

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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Position Quality Account Manager
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NXP Quality Management Team.

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